

SOT1896-1

X2QFN16; plastic, thermal enhanced super thin quad flat package; no leads;
16 terminals; 1.6 mm x 1.6 mm x 0.35 mm body

26 September 2025

Package information



1 Package summary

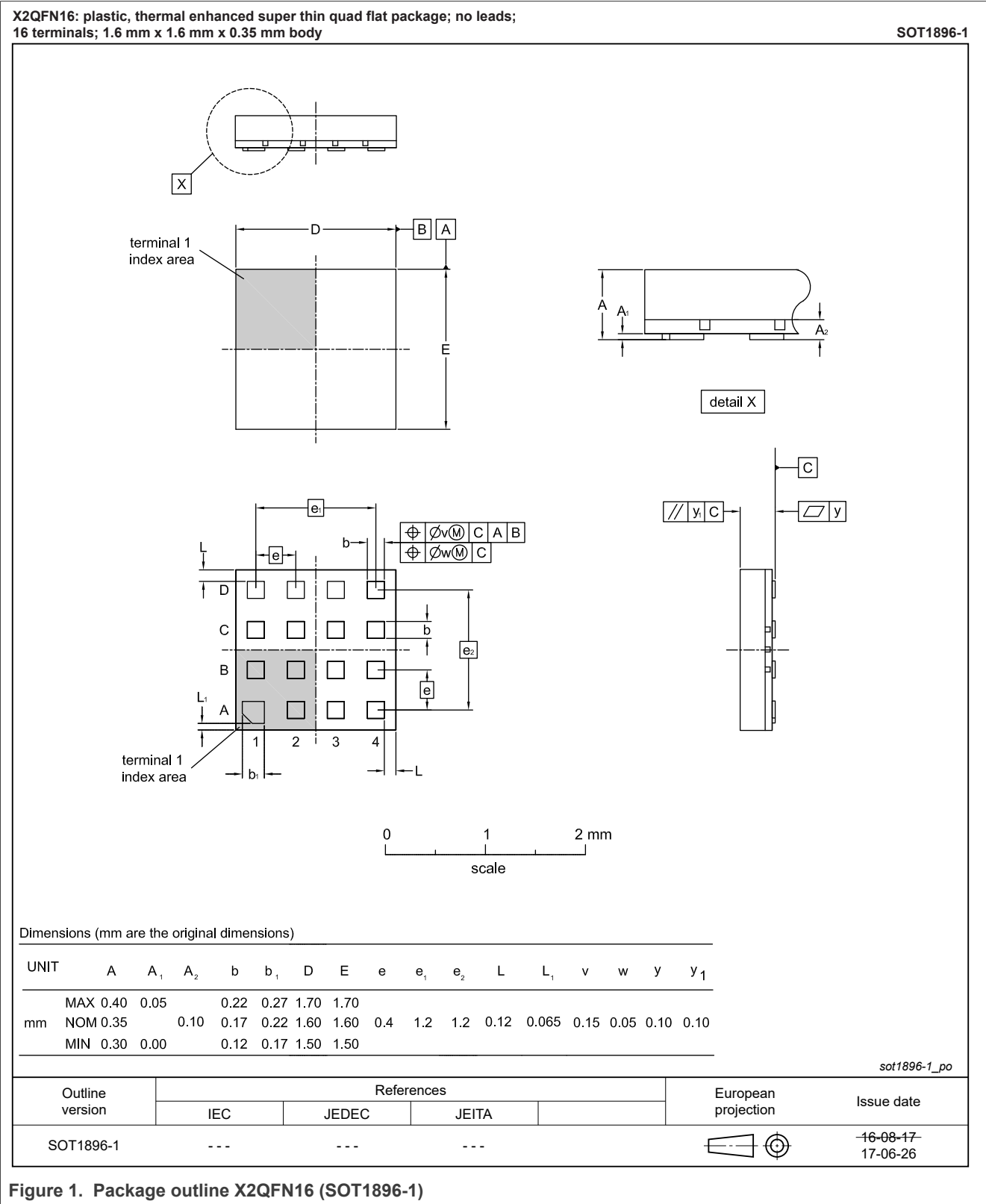
Terminal position code	Q (quad)
Package type descriptive code	X2QFN16
Package type industry code	X2QFN
Package style descriptive code	X2QFN (super thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-06-2017

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.5	1.6	1.7	mm
package width	1.5	1.6	1.7	mm
seated height	0.3	0.35	0.4	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	16	-	

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2 Package outline



**X2QFN16; plastic, thermal enhanced super thin quad flat package; no leads; 16 terminals; 1.6 mm
x 1.6 mm x 0.35 mm body**

3 Soldering

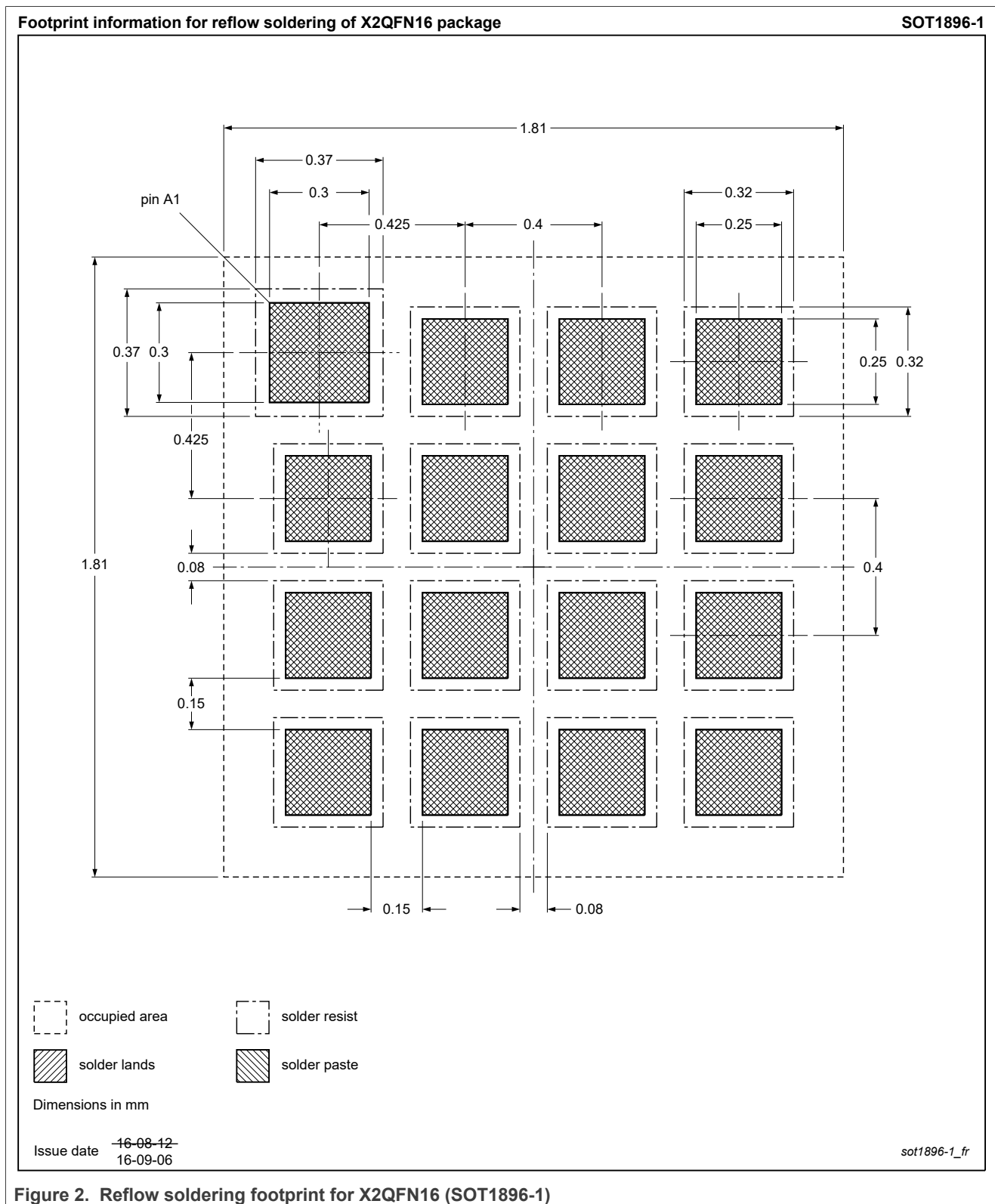


Figure 2. Reflow soldering footprint for X2QFN16 (SOT1896-1)

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4 Legal information

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